

## NDT014

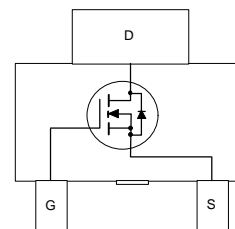
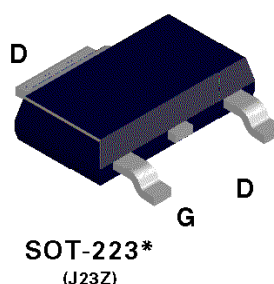
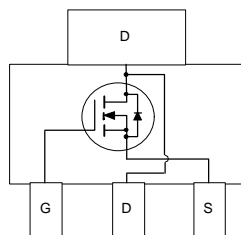
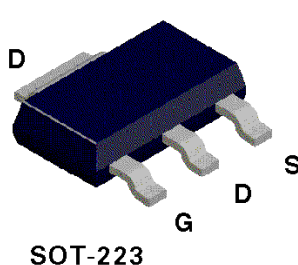
### N-Channel Enhancement Mode Field Effect Transistor

#### General Description

Power SOT N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance and provide superior switching performance. These devices are particularly suited for low voltage applications such as DC motor control and DC/DC conversion where fast switching, low in-line power loss, and resistance to transients are needed.

#### Features

- 2.7A, 60V.  $R_{DS(ON)} = 0.2\Omega$  @  $V_{GS} = 10V$ .
- High density cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handling capability in a widely used surface mount package.



#### Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	NDT014	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current - Continuous (Note 1a)	$\pm 2.7$	A
	- Pulsed	$\pm 10$	
$P_D$	Maximum Power Dissipation (Note 1a)	3	W
	(Note 1b)	1.3	
	(Note 1c)	1.1	
$T_J, T_{STG}$	Operating and Storage Temperature Range	-65 to 150	$^\circ\text{C}$

#### THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	42	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	12	$^\circ\text{C/W}$

\* Order option J23Z for cropped center drain lead.

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			25	μA
		V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> =125°C			250	μA
I <sub>GSSF</sub>	Gate - Body Leakage, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate - Body Leakage, Reverse	V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V			-100	nA
ON CHARACTERISTICS (Note 2)						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	3	4	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.6 A		0.18	0.2	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 1.6 A		2		S
DYNAMIC CHARACTERISTICS						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz		155		pF
C <sub>oss</sub>	Output Capacitance			60		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			15		pF
SWITCHING CHARACTERISTICS (Note 2)						
t <sub>D(on)</sub>	Turn - On Delay Time	V <sub>DD</sub> =30 V, I <sub>D</sub> = 10 A, V <sub>GEN</sub> = 10 V, R <sub>GEN</sub> = 24 Ω		10	20	ns
t <sub>r</sub>	Turn - On Rise Time			64	100	ns
t <sub>D(off)</sub>	Turn - Off Delay Time			10	20	ns
t <sub>f</sub>	Turn - Off Fall Time			10	20	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 48 V, I <sub>D</sub> = 10 A, V <sub>GS</sub> = 10 V		5	11	nC
Q <sub>gs</sub>	Gate-Source Charge			1.2	3.1	nC
Q <sub>gd</sub>	Gate-Drain Charge			2	5.8	nC

Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				2.7	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				22	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 2.7A (Note 2)		0.95	1.6	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>F</sub> = 10 A, dI <sub>F</sub> /dt = 100 A/μs			140	ns

Notes:

1. R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θJC</sub> is guaranteed by design while R<sub>θCA</sub> is determined by the user's board design.

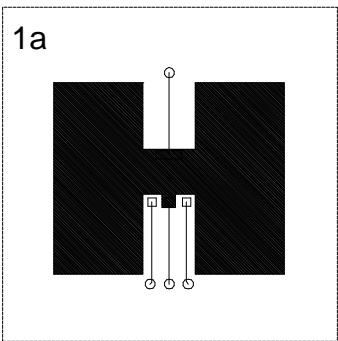
$$P_D(t) = \frac{T_J - T_A}{R_{\theta JA}(t)} = \frac{T_J - T_A}{R_{\theta J} + R_{\theta CA}(t)} = I_D^2(t) \times R_{DS(on)} @ T_J$$

Typical R<sub>θJA</sub> using the board layouts shown below on 4.5"x5" FR-4 PCB in a still air environment:

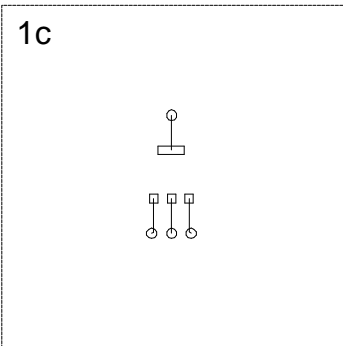
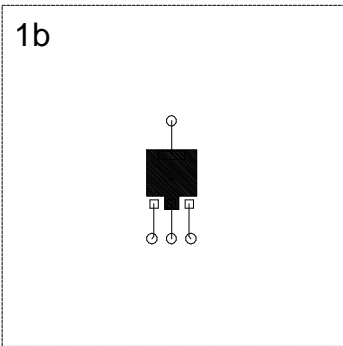
a. 42°C/W when mounted on a 1 in<sup>2</sup> pad of 2oz copper.

b. 95°C/W when mounted on a 0.066 in<sup>2</sup> pad of 2oz copper.

c. 110°C/W when mounted on a 0.0123 in<sup>2</sup> pad of 2oz copper.



Scale 1 : 1 on letter size paper



2. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%.

## Typical Electrical Characteristics

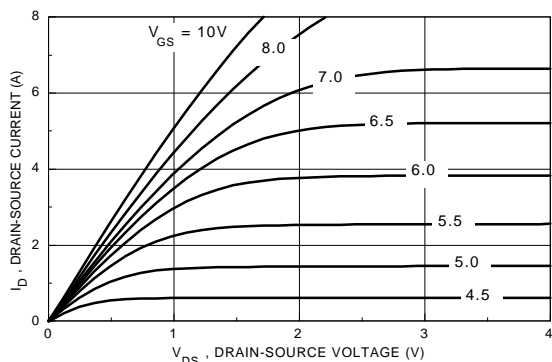


Figure 1. On-Region Characteristics.

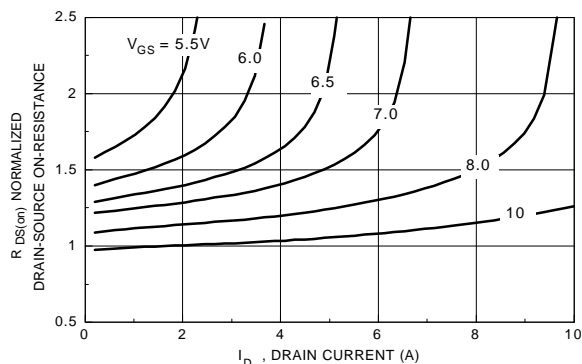


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

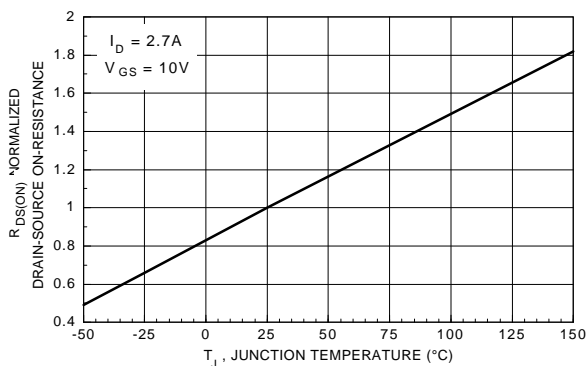


Figure 3. On-Resistance Variation with Temperature.

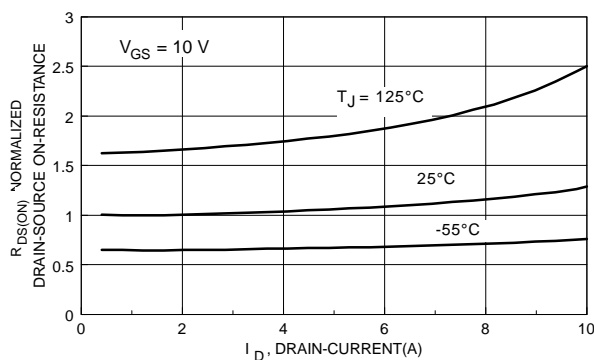


Figure 4. On-Resistance Variation with Drain Current and Temperature.

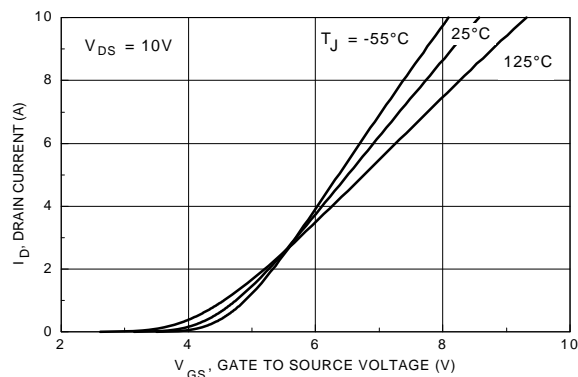


Figure 5. Transfer Characteristics.

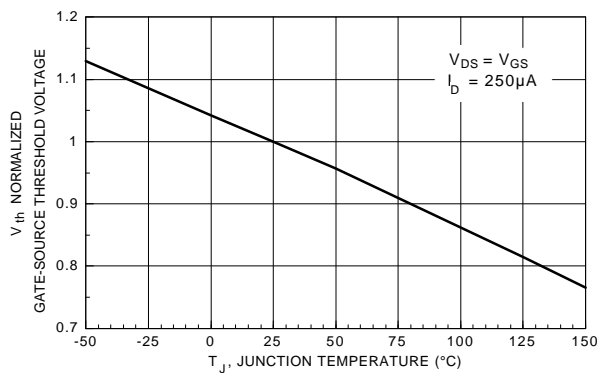
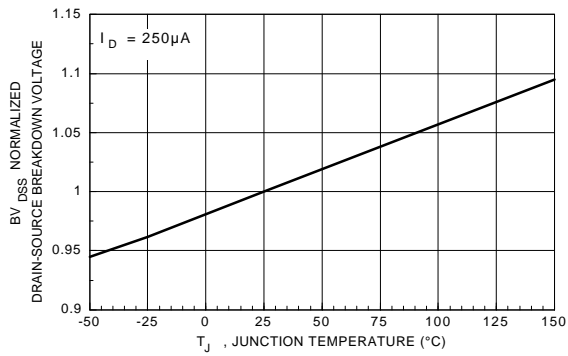
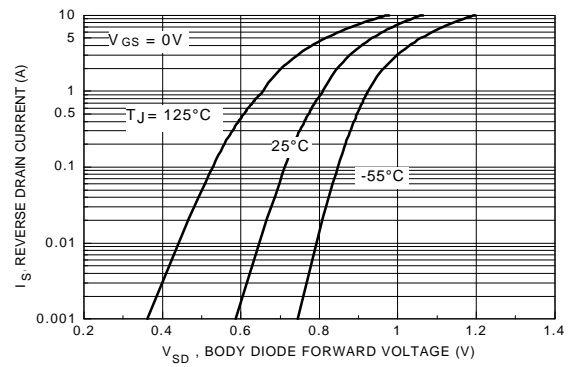


Figure 6. Gate Threshold Variation with Temperature.

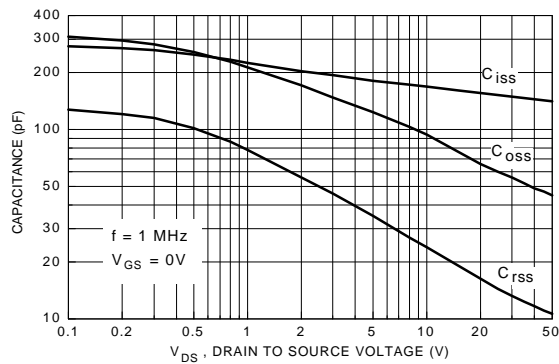
## Typical Electrical Characteristics (continued)



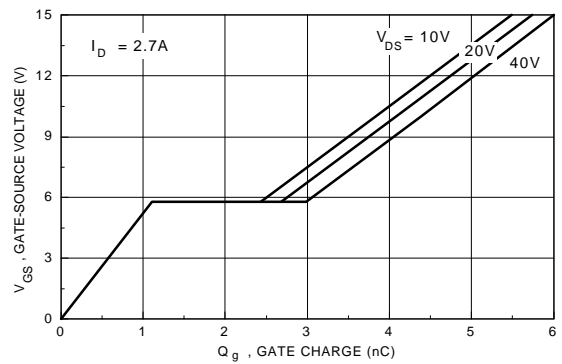
**Figure 7. Breakdown Voltage Variation with Temperature.**



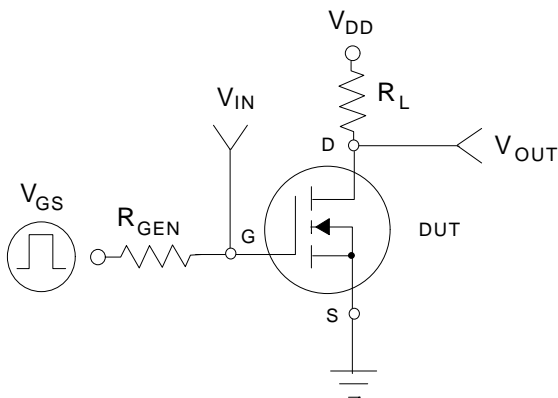
**Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.**



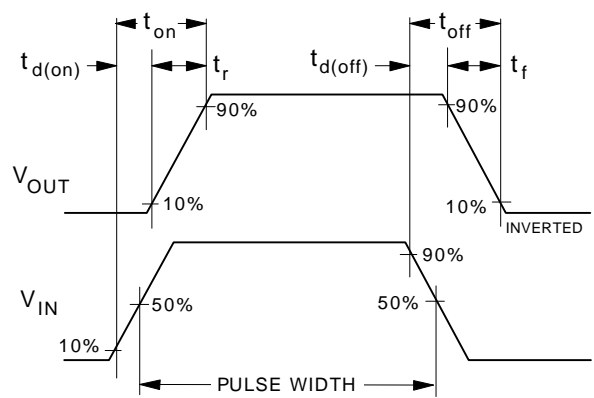
**Figure 9. Capacitance Characteristics.**



**Figure 10. Gate Charge Characteristics.**

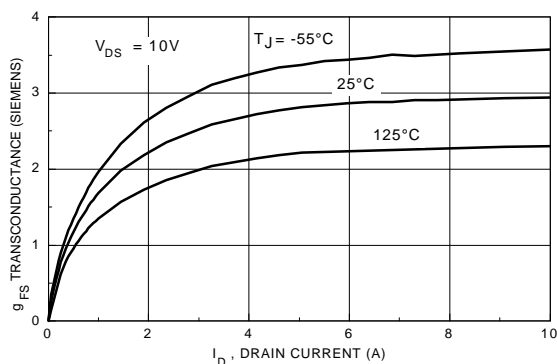


**Figure 11. Switching Test Circuit.**

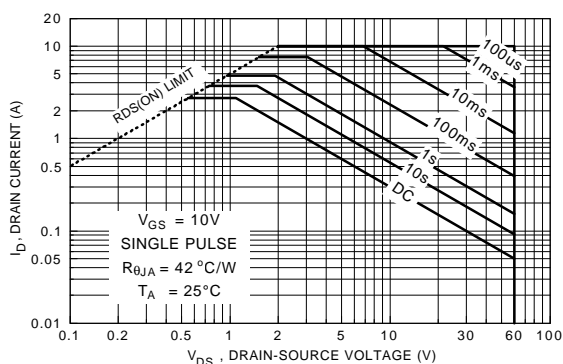


**Figure 12. Switching Waveforms.**

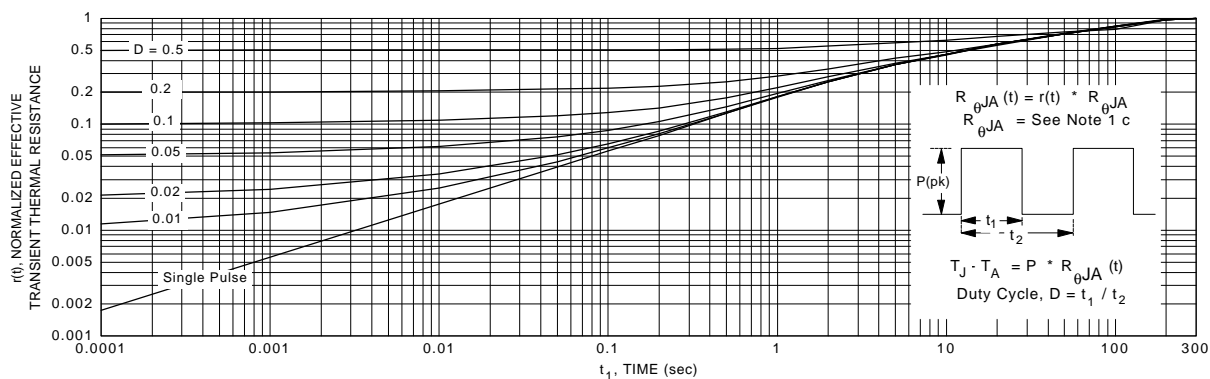
## Typical Electrical Characteristics (continued)



**Figure 13. Transconductance Variation with Drain Current and Temperature.**



**Figure 14. Maximum Safe Operating Area.**



**Figure 15. Transient Thermal Response Curve.**

Note: Thermal characterization performed using the conditions described in note 1c. Transient thermal response will change depending on the circuit board design.

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